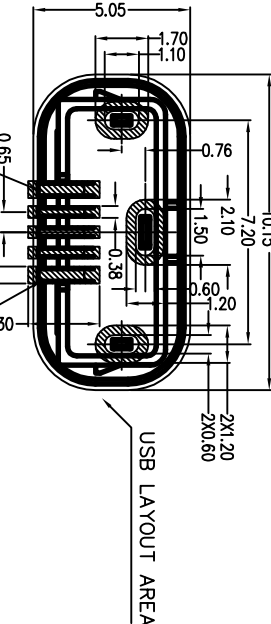
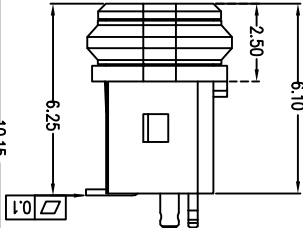
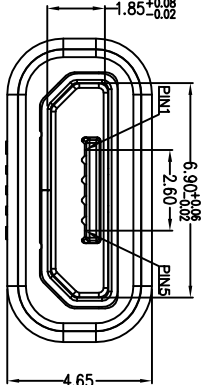
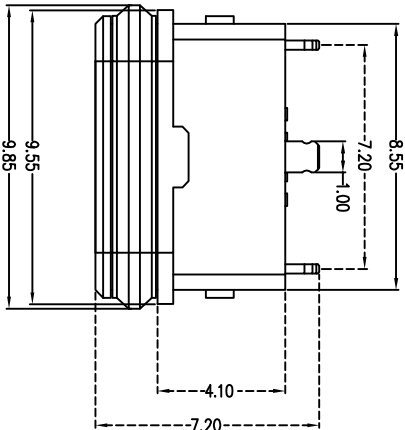
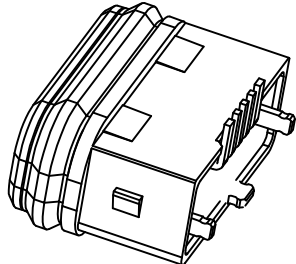


RoHS 客户图

目錄 MAPX	變更內容 MODIFICATION	日期 DATE
A0	NEW	09-10-20



- Note:
- 1.Material:
- 1.1 Housing: High temperature thermoplastic
 - 1.2 Contact: copper alloy,t=0.20mm
 - 1.3 Shell: SUS304,t=0.30mm
 - 1.4 cover: High temperature thermoplastic
 - 1.5 Ring: SILICON
 - 1.6 Epoxy: Epoxy
- 2.Specification:
- 2.1 Current rating:1.5PIN 2.0A Max/2,3,4PIN 1A Max.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 mΩ Max.
 - 2.4 Insulation resistance: 100 MΩ Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min.
 - 2.7 Temperature range: -30℃~80℃
 - 2.8 Waterproof: IPX8.

RECOMMEND PCB LAYOUT
PCB圖只做參考

產品圖 PRODUCT CHART DWG				深圳市鑫风雷电子有限公司			
公差一览表 TOLERANCE UNLESS OTHERWISE				單位 UNITS	制圖 DRAWING	王冠	產品料號 PRODUCT PART NO.
X	±0.30	X'	±5°	1:1	审核	雷永健	25001-UMKF003-F
.X	±0.25	.X'	±2°	SCALE	核准	雷永健	產品名稱 PRODUCT NO.
.XX	±0.30	.XX'	±1°	DATE	2009/10/20	雷永健	MICRO 5S B TYPE 180度SMT 防水 H=6.1
.XXX	±0.15	.XXX'	±0.5°	DATE	2009/10/20	雷永健	角法 VIEW
							版本 VER
							A0